PRESS RELEASE
January 2025

IMAPS Device Packaging Conference and Advanced Packaging for Medical Microelectronics Workshop to Co-locate

Both events to take place March 3-7, 2025 in Phoenix, Arizona

Device Packaging Conference - The event with the most advanced packaging content this winter

The 21th Annual Device Packaging Conference (DPC 2025) will be held March 3-6, 2025, at the Sheraton Grand at Wild Horse Pass in Phoenix, Arizona. This esteemed event brings together industry engineers, researchers and top experts involved in advanced packaging and microelectronics assembly with a multi-faceted technical program and unique networking events.

This year's General Chair, Amy Lujan with SavanSys, comments: "2025 will be an exciting year for Device Packaging. To kick off the conference's third decade, we're in a new location that gives us room to grow our exhibit hall and technical program. In addition to our popular tracks focused on 2D/3D heterogeneous integration, flip chip, and fan-out / wafer-level packaging, there will be a greater focus on emerging technologies and applications that are driving advancements in packaging."

The technical content includes an unrivaled, concurrent 4-track program and interactive poster session, with 116 speakers. Attendees will hear from keynote speakers from Absolics, IBM, and ScaleFlux. An evening panel discussion is planned on "Preparing for the Coming AI Winter" and a business plenary session will focus on "Scaling of AI from Datacenter to Consumer".

Attendees can also register for 17 Professional Development Courses that will be held on Monday, March 3. These focused courses provide a learning opportunity for looking to enhance their skills and knowledge, or those new to the industry.

A sold-out exhibit hall will showcase the latest products, technologies, and applications. Registration includes networking opportunities that promote attendee interaction: welcome and exhibit hall receptions, group lunches, poster session happy hour, and the 2nd annual 3D InCites Back Yard Olympics following the poster session. A post-conference golf scramble will be offered to raise funds for the IMAPS Microelectronics Foundation.

In 2024, DPC welcomed the highest attendance in its 20-year history. With the expanded facility, 2025 is expected to be record breaking once again. Visit the DPC 2025 page for details and registration.

Advanced Packaging for Medical Microelectronics Workshop

On March 5-7, this advanced technology workshop will bring together technologists in semiconductor packaging with life science experts interested in applying advanced packaging methods to enable the next generation of medical microelectronic devices. It will draw invited experts in the fields of medicine, medical

devices, biomaterials, microelectronics, semiconductor packaging, and product assembly and will cover topics involving technologies, products, strategies, current and emerging markets, and collaborations in areas such as Disease Detection, Materials, Assembly and Applications/Products.

The event will kick off with a combined poster session (with DPC 2025) on March 5, followed by the technical program on March 6 and 7.

Three keynotes will present on: “Inspire: A Story of Growth” (Dave Dieken, Inspire Medical Systems), “RF Packaging and Integrated Antennas for Low-Cost Medical Radar Sensor Systems” (Ivan Ndip, Fraunhofer IZM/Brandenburg Univ. of Technology) and “The Economics of Small Medical Implants” (Rex Hales, Cirtec Medical).

A discount is available if attending both the Medical and DPC events. To learn more, visit the Medical workshop page.

About IMAPS

The International Microelectronics Assembly and Packaging Society is the largest society dedicated to the advancement and growth of microelectronics and electronics packaging. Worldwide, IMAPS offers educational and marketing opportunities for industry professionals, packaging organizations, and students through technical conferences and workshops, professional development courses, IMAPSource microelectronics packaging research library, local chapters, and exhibitions. The Society encompasses a wide-range of technologies and topics critical to microelectronics assembly and packaging, including: on-shoring, heterogenous integration, fan-out wafer level packaging, 2.5D/3D technologies, system-in-package, photonics/optical, power packaging, CPI, package design/modeling, interconnects, wire bonding, flip chip, MEMS, sensors, packaging for 5g/6g, RF/wireless, signal/power integrity, advanced materials, substrates and more.

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